

What is claimed is:

1. A semiconductor device comprising a first semiconductor chip and a second semiconductor chip superposed on and bonded to a surface of the first semiconductor chip,

5 wherein, in a region on the surface of the first semiconductor chip where the second semiconductor chip is bonded to the first semiconductor chip, chip connection portions are arranged in standardized positions so as to fit a plurality of predetermined types of semiconductor chips, and

wherein, on the second semiconductor chip, chip connection portions are
10 arranged in standardized positions so as to fit the chip connection portions arranged on the first semiconductor chip.

2. A semiconductor device as claimed in claim 1,

wherein the plurality of predetermined types of semiconductor chips have
15 identical functions but are of different grades.

3. A semiconductor chip having, on a surface thereof, a chip bonding region that fits one of a plurality of predetermined types of semiconductor chips,

wherein, in the chip bonding region, chip connection portions are arranged
20 in standardized positions so as to fit any of the plurality of predetermined types of semiconductor chips.

4. A semiconductor chip as claimed in claim 3,

wherein, on the plurality of predetermined types of semiconductor chips, chip connection portions are arranged in positions corresponding to the standardized positions.

5 5. A semiconductor chip as claimed in claim 3,
 wherein the plurality of predetermined types of semiconductor chips have identical functions but are of different grades.

 6. A semiconductor chip having a plurality of chip connection portions
10 formed on a surface thereof,
 wherein the plurality of chip connection portions are arranged in positions standardized among a plurality of predetermined types of semiconductor chips.

 7. A semiconductor chip as claimed in claim 6,
15 wherein the plurality of predetermined types of semiconductor chips have identical functions but are of different grades.